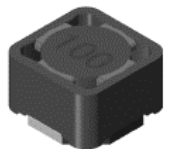


MATERIAL DECLARATION SHEET



Material Number	SRR1260A series			
Product Line	Shielded SMD Power Inductor			
Compliance Date	2024/1/24			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	DR + RI CORE	Ferrite	1.231	Iron oxide (Fe ₂ O ₃)	1309-37-1	52.0%	18.289%	35.18
				Zinc oxide (ZnO)	1314-13-2	15.0%	5.276%	
				Cupric oxide(CuO)	1317-38-0	17.0%	5.979%	
				Nickel oxide (NiO)	1313-99-1	16.0%	5.627%	
2	WIRE	Copper	1.33	Copper(Cu)	7440-50-8	100.0%	38.000%	40.00
		Resin	0.07	Polyurethane Resin	9009-54-5	100.0%	2.000%	
3	Base	Resin	0.51	Aromatic polyester resin	60088-52-0	60.0%	8.743%	14.57
				Glass fiber	65997-17-3	38.0%	5.537%	
				Carbon Black	1333-86-4	2.0%	0.291%	
		Copper	0.12	Copper (Cu)	7440-50-8	93.6%	3.209%	3.43
				Tin (Sn)	7440-31-5	6.2%	0.213%	
				Phosphorus(P)	7723-14-0	0.2%	0.007%	
Plating- Sn	0.026	Tin (Sn)	7440-31-5	100.0%	0.731%	0.91		
Plating- Ni	0.006	Nickel (Ni)	7440-02-0	100.0%	0.183%			
4	Adhesive	Epoxy	0.02	reaction mixture of epichlorohydrin and bis-phenol A	25068-38-6	65.0%	0.371%	0.57
				Calcium Carbonate	1317-65-3	35.0%	0.200%	
5	Adhesive	Epoxy	0.13	Epoxy Resins	61788-97-4	84.2%	3.127%	3.71
				Silicon	7440-21-3	15.8%	0.587%	

MATERIAL DECLARATION SHEET



6	Solder	Tin	0.012	Tin (Sn)	7440-31-5	100.0%	0.343%	0.34
7	Tape	Tape	0.045	1,3-Benzenedicarbonyl dichloride, polymer with 1,3-benzenediamine	25765-47-3	96.0%	1.234%	1.29
				Ammonium polyphosphate	68333-79-9	1.0%	0.013%	
				2-Propenoic acid, polymer with butyl 2-propenoate and ethenyl acetate	25085-41-0	3.0%	0.039%	
		Total weight	3.5					

This Document was updated on: 2024/1/24

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.